

FILED ELECTRONICALLY ON 22 MAY 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS)	
)	Examiner: Chris C. CHU
Application No.: 10/632,552)	
)	Group Art Unit: 2815
Filed: August 2, 2003)	
)	Date: <u>May 22, 2006</u> .
Title: Semiconductor multi-package module having)	
package stacked over die-up flip chip)	
ball grid array package and having wire)	
bond interconnect between stacked packages)	
)	

MAIL STOP AMEMDMENT
COMMISSIONER FOR PATENTS
P.O BOX 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed December 20, 2005, kindly amend the application as follows.

Amendments to the Claims are reflected in the **Listing of Claims** which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.